

REMARKS

Applicants wish to thank the courtesies extended to the undersigned during the telephone interview. An Interview Summary accompanies this response.

Applicants submit new prior art for consideration by the Office. The new art is cited in the enclosed Information Disclosure Statement.

Applicants hereby add new claims 86-89 and cancel claims 3-4, 12, 20-21, and 82. Accordingly, claims 1-2, 5-11, 13-19, 22-30, 32-34, 67-81, and 83-89 are pending in the present application.

Claims 1-30, 32-34, and 67-85 stand rejected under 35 USC 103(a) for obviousness over U.S. Patent No. 6,278,264 to Burstein et al.

Applicants respectfully traverse the rejection and urge allowance of the present application.

Claim 1 has been amended to include limitations of claims 3 and 4 as discussed during the telephonic interview. Burstein fails to disclose or suggest the positively-recited *horizontal interconnect layer of the substrate of claim 1*. Accordingly, claim 1 recites limitations which are not shown nor suggested by Burstein and claim 1 is allowable.

The claims which depend from independent claim 1 are in condition for allowance for the reasons discussed above with respect to the independent claim as well as for their own respective features which are neither shown nor suggested by the cited art.

Claim 17 includes limitations of claims 20 and 21. Claim 17 recites the

horizontal interconnect layer formed upon and coupled with the at least one metallization layer of the power semiconductor device. Claim 17 recites limitations not shown nor suggested by the prior art and claim 17 is allowable.

The claims which depend from independent claim 17 are in condition for allowance for the reasons discussed above with respect to the independent claim as well as for their own respective features which are neither shown nor suggested by the cited art.

Applicants add new claims 86-89. New claim 86 is supported by paragraph 62 of the originally-filed application. New claim 87 is supported by paragraph 86 of the originally-filed application.

New claim 88 includes limitations of claims 1, 10 and 82 as previously pending. Claim 88 defines a vertical laminate package not shown nor suggested by Burstein as discussed during the telephone interview. Claim 88 recites limitations not shown nor suggested by the prior art and claim 88 is allowable.

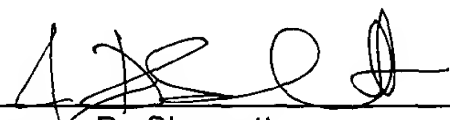
New claim 89 includes limitations of claims 1 and 69 as previously pending. Claim 89 defines the source contacts and the drain *contacts of the package arranged in a checkerboard pattern* not shown nor suggested by the prior art. Claim 89 recites limitations not shown nor suggested by the prior art and claim 89 is allowable.

Applicants respectfully request allowance of all pending claims.

The Examiner is requested to phone the undersigned if the Examiner believes such would facilitate prosecution of the present application. The undersigned is available for telephone consultation at any time during normal business hours (Pacific Time Zone).

Respectfully submitted,

Dated: 8/5/03

By: 
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